

ARS50 / AR50

50.0 AMPS. High Current Plastic Silicon Rectifiers



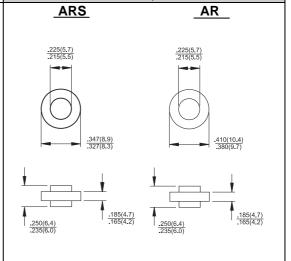
Voltage Range 50 to 1000 Volts Current 50.0 Amperes

Features

- Plastic material used carries Underwriters Laboratory Classification 94V-O
- Low cost construction utilizing void-free molded plastic technique
- ♦ Low cost
- ♦ Diffused junction
- ♦ Low leakage
- ♦ High surge capability
- High temperature soldering guaranteed: 260°C for 10 seconds

Mechanical Data

- Case: Molded plastic case
- Terminals: Plated terminals, solderable per MIL-STD-202. Method 208
- ♦ Polarity: Color ring denotes cathode end
- ♦ Weight: 0.07 ounce, 1.8 grams
- Mounting position: Any



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	ARS 50A	ARS 50B	ARS 50D	ARS 50G	ARS 50J	ARS 50K	ARS 50M	- Units
		AR 50A	AR 50B	AR 50D	AR 50G	AR 50J	AR 50K	AR 50M	
Maximum Recurrent Peak Revere Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @Tc = 135° C	I _(AV)	50							Α
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method) at T _J =150°C	I _{FSM}	500							Α
Maximum Instantaneous Forward Voltage @ 50A	V _F	1.1							٧
Maximum DC Reverse Current @ Tc=25°C	I _R				5.0				uA
at Rated DC Blocking Voltage @ Tc=100℃	-10	250							uA
Typical Reverse Recovery Time (Note 2)	Trr	3.0							uS
Typical Junction Capacitance (Note 1) $T_J=25^{\circ}C$	Cj	300							pF
Typical Thermal Resistance (Note 3)	$R\theta_{JC}$	1.0							C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-50 to +175							Ç

- Notes: 1. Measured at 1 MHz and Applied Reverse Voltage of 4.0 V D.C.
 - 2. Reverse Recovery Test Conditions: I_F=0.5A, I_R=1.0A, I_{RR}=0.25A
 - 3. Thermal Resistance from Junction to Case, Singe Side Cooled.



